

PATENT ASSIGNMENT

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NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Shigeo IDE	06/27/2011
Akihiro NIIMI	06/27/2011
RECEIVING PARTY DATA	
Name:	DENSO CORPORATION
Street Address:	1-1 Showa-cho
City:	Kariya-city, Aichi-pref.
State/Country:	JAPAN
Postal Code:	448-8661
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13173347
CORRESPONDENCE DATA	
Fax Number:	(703)816-4100
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	703-816-4000
Email:	jam@nixonvan.com
Correspondent Name:	NIXON & VANDERHYE, PC
Address Line 1:	901 NORTH GLEBE ROAD, 11TH FLOOR
Address Line 4:	ARLINGTON, VIRGINIA 22203
ATTORNEY DOCKET NUMBER:	MNL-2635-1035
NAME OF SUBMITTER:	Michelle N. Lester
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REEL: 026529 FRAME: 0036

ASSIGNMENT OF PATENT APPLICATION

(Inventors)

1) Shigeo IDE	_____
2) Akihiro NIIMI	_____
3)	_____
4)	_____
5)	_____
6)	_____

In consideration of the sum of one dollar (\$1.00) and other good and valuable considerations paid to each of the undersigned, the undersigned agree(s) to assign, and hereby does assign, transfer and set over to

(Assignee)
(Address) DENSO CORPORATION, a corporation of Japan having a place of business at
1-1 Showa-cho, Kariya-city, Aichi-pref. 448-8661 Japan

(hereinafter designated as the Assignee) the undersigned's entire right, title and interest for the United States, its territories, dependencies and possessions, and for the country of

(Other
Countries) in the invention, and all application for patent and any Letters Patent which may be granted therefore, known as

(Title) SEMICONDUCTOR DEVICE

for which the undersigned has (have) executed on even date herewith an application for patent in the United States of America or, if not on even date, then has executed on June 27, 2011 or has already filed in U.S. appln. Serial No. _____, filed on _____

The undersigned acknowledges an obligation of assignment of this invention to said assignee at the time the invention was made.

The undersigned agree(s) to execute all papers and documents necessary in connection with the application or any interference which may be declared and any continuing or divisional applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient and further to perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patent of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the firm of NIXON & VANDERHYE P.C. the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document. It is understood and agreed that ASSIGNEE'S attorneys Nixon & Vanderhya P.C. have represented only ASSIGNEE and will continue to represent only ASSIGNEE with respect to this invention.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned signature(s).

Date June 27, 2011 Signature of Inventor Shigeo Ide
Shigeo Ide

Date June 27, 2011 Signature of inventor Akihiro Niimi
Akihiro Niimi

Date _____ Signature of Inventor _____

Date _____ Signature of inventor _____

Date _____ Signature of inventor _____

Date _____ Signature of inventor _____

Witnessed by: Yasushi Bokura Date June 27, 2011

Witnessed by: Yasushi Bokura Date June 27, 2011

Witnessed by: _____ Date _____

Witnessed by: _____ Date _____